

【DOCUMENT NAME 】 ABSTRACT

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【OBJECT】 The present invention aims to provide a high-frequency ceramic package, adapted for an additional heat-sinking level of a ceramic package and further for a decrease in the occurrence of a curl.

【CONSTRUCTION】 A high-frequency ceramic package 10 includes a ring-shaped ceramic frame plate 12 whose surface is brazed to a surface of a jointed metal plate 11, the jointed metal plate 11 including first and second metal plates 17, 18 in which the first metal plate 17 forms a substantially rectangular shape, the first metal plate 17 having fixing holes defined at both ends in a longitudinal direction thereof and further having a hollowed portion 19 formed at a central portion thereof, while the second metal plate 18 is fitted in the hollowed portion 19 of the first metal plate 17 in a state in which the first and second metal plates 17 and 18 are jointed together in an end-to-end relationship, thereby forming the jointed metal plate 11, wherein one material that forms the first metal plate 17 differs in thermal expansion coefficient from another material that forms the second metal plate 18, a cavity 16 that is formed by a concave surrounded by the second metal plate 18 and the ring-shaped ceramic frame plate 12 has a semiconductor electronic component mounting portion 16a on a bottom thereof, and the second metal plate 18 is made from a material having an elevated degree of heat-sinking characteristics.

【SELECTED DRAWING】 FIG. 1